

IN THE CLAIMS:

Please note that all claims currently pending and under consideration in the referenced application are shown below. This listing of claims will replace all prior versions and listings of claims in the application.

Please amend claim 16 as set forth hereinbelow.

Listing of Claims:

1. (Previously Presented) A method of fabricating an integrated circuit package, the method comprising:
providing a semiconductor die having a plurality of conductive pads;
forming a leadframe including at least two conductors, each conductor of the at least two conductors having a first end and a second end and a generally arcuate-shaped portion between the first and second ends, at least a portion of each generally arcuate-shaped portion exhibiting a constant radius;
configuring and positioning the at least two conductors such that line spacing between each of the at least two conductors is constant from their respective first ends to their respective second ends;
electrically coupling the first ends of each of the at least two conductors with at least one of the plurality of conductive pads; and
encapsulating the semiconductor die and at least a portion of the at least two conductors with an insulating material.
2. (Previously Presented) The method according to claim 1, wherein forming the at least two conductors further comprises forming a first conductor to exhibit a first arc length through its generally arcuate-shaped portion and forming a second conductor to exhibit a second arc length through its generally arcuate-shaped portion wherein the first arc length is different than the second arc length.

3. (Previously Presented) The method according to claim 1, wherein forming the at least two conductors further comprises forming each generally arcuate-shaped portion of each of the at least two conductors to exhibit a different arc length than any other generally arcuate-shaped portion of any other conductor of the at least two conductors.

4. (Previously Presented) The method according to claim 1, wherein forming the at least two conductors includes forming the generally arcuate-shaped portion of at least one of the at least two conductors to include a plurality of segments including at least one straight segment and at least one generally arcuate segment.

5. (Original) The method according to claim 4, wherein the plurality of segments includes at least three segments.

6. (Original) The method according to claim 4, further comprising defining at least one segment of the plurality of segments to exhibit a different length than at least one other segment of the plurality of segments.

7. (Previously Presented) The method according to claim 1, wherein forming the at least two conductors includes forming at least one conductor of the at least two conductors such that the generally arcuate-shaped portion is a substantial portion of the at least one conductor.

8. (Previously Presented) The method according to claim 1, wherein forming the at least two conductors includes forming at least one conductor of the at least two conductors such that the generally arcuate-shaped portion exhibits a constant radius throughout an entire arc length thereof.

9. (Cancelled)

10. (Original) The method according to claim 1, further comprising configuring the first and second ends of each of the at least two conductors to be positioned at orientations of substantially 90° relative to each other.

11. (Original) The method according to claim 1, further comprising configuring the generally arcuate-shaped portion of each of the at least two conductors to exhibit a substantially 90° arc.

12.-15. (Cancelled)

16. (Currently Amended) A method of fabricating an integrated circuit package, the method comprising:
providing a semiconductor die having a plurality of conductive pads;
forming a leadframe including at least two conductors, each conductor of the at least two conductors having a first end and a second end and a generally arcuate-shaped portion between the first and second ends, at least a portion of each generally arcuate-shaped portion exhibiting a constant radius, and forming the generally arcuate-shaped portion of at least one of the at least two conductors to include a plurality of segments including at least one straight segment and at least one generally arcuate segment;
configuring and positioning the at least two conductors such that line spacing between the generally arcuate-shaped portion of each of the at least two conductors is constant from their respective first ends to their respective second ends;
electrically coupling the first ends of each of the at least two conductors with at least one of the plurality of conductive pads; and
encapsulating the semiconductor die and at least a portion of the at least two conductors with an insulating material.

17. (Previously Presented) The method according to claim 16, wherein the plurality of segments includes at least three segments.

18. (Previously Presented) The method according to claim 16, further comprising defining at least one segment of the plurality of segments to exhibit a different length than at least one other segment of the plurality of segments.